

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6217xxxxGR-G
Typical Mass: 3 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.228	Silicon	76100	7440-21-3
	-	Arsenic	4	7440-38-2
Lead pad	0.610	Nickel	203300	7440-02-0
	0.028	Silver	9300	7440-22-4
	0.006	Gold	2000	7440-57-5
Die attach	0.012	Silver	4000	7440-22-4
	0.003	Epoxy Resin	1000	—
	0.001	Phenol Resin	300	—
Bonding wire	0.059	Gold	19700	7440-57-5
Resin	1.797	Silica	598900	60676-86-0
	0.103	Epoxy Resin	34200	—
	0.092	Phenol Resin	30800	—
	0.061	Metal Hydroxide	20400	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."